

RE EMBEDDED CONTROLLERS

SILICON ON THIN BURIED OXIDE
RENESAS'S NEXT GENERATION ULTRA
LOW POWER PROCESS

RENESAS ELECTRONICS EUROPE
JUNE 2020



AGENDA

- Introduction
- What is Silicon on Thin Buried Oxide
- Renesas RE Embedded Controller Roadmap
 - RE detailed features
- Features of RE Embedded Controllers
 - Unique Low Power features
 - Energy Harvesting support
- Summary



RENESAS PRODUCT PORTFOLIO

Analog/Power/SOC Devices



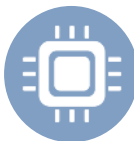
Power

- Industrial & Automotive
- IGBT, diodes and Intelligent Power Modules



Analog

- Industrial & Automotive
- DC to DC, Fuel gauge, charging, CMOS Image Sensors, Optical Image Stabilizer, SL BLDC Motor



SOC/ASIC

- Powertrain Control
- ASSP for USM, USB PD and PLC
- Custom ASICs
- ASIC, broad IP portfolio in 40 nm, 28 nm, 16 nm

Microcontroller Devices and Solutions



Scalable Automotive solutions for Infotainment, Cluster and ADAS

- 47000 DMIPs, Multimedia, SoC



Automotive High end solution

- 1344 DMIPS, Real Time



Industry standard

- Industrial, and consumer solutions
- Enhanced security



Ultra Low Power Controllers

- Wearables, sensor and Energy Harvesting
- 20 - 35 μ A/MHz, 140 nA standby



Proprietary Industrial consumer

- 480 DMIPS, FPU, DSC
- 100 μ A/MHz, 350 nA standby



Industrial Automotive solutions

- 25000 DMIPS, Linux, Android
- Industrial connectivity



16-bit Industrial & Automotive,

- 44 DMIPS, True Low Power
- 66 μ A/MHz, 220 nA standby

Microcontroller Platform



RENESAS SYNERGY™ PLATFORM

Solutions Gallery

Software

Development Tools

Synergy Software Package

Software Add Ons







Hardware

Kits

Microcontrollers

- Integrated Software, Development Tools, MCUs, Solutions
- Industrial 130 nm and 40 nm

RENESAS MCU/MPU LINEUP

8/16bit MCU	32bit MCU				32/64bit MPU
Renesas Core		Arm® Core			
					
Low Power	Power Efficiency	Arm® Ecosystem	Arm® Ecosystem	Qualified Platform	High Performance
<p>Features: Ultra-low energy Low pin count lineup available</p> <p>Max operating frequency: 20-32MHz</p> <p>Applications: General-purpose Sensor Motor Control LCD Display Bluetooth® Low Energy Sub-GHz Wireless Communication Security</p>	<p>Features: Superior power efficiency High-capacity flash memories Broad lineup</p> <p>Max operating frequency: 32-240MHz</p> <p>Applications: General-purpose Motor Control Security Capacitive Touch Battery Powered LCD Control Industrial Network Cloud Connectivity</p>	<p>Features: High efficiency Security</p> <p>Max operating frequency: 48-200MHz</p> <p>Applications: Motor Control LCD Control Network Capacitive Touch Security</p>	<p>Features: Ultra Low Energy Low Voltage operation Large memory Energy Harvesting Security</p> <p>Max operating frequency: 64MHz</p> <p>Applications: Building Automation Home Automation IoT Sensors Medical User Interfaces Wearables</p>	<p>Features: Qualified software and tools</p> <p>Max operating frequency: 32-240MHz</p> <p>Applications: Motor Control LCD Control Network IoT Devices Security</p>	<p>Features: Multi-core up to 8 cores Linux or RTOS available High-capacity on-chip RAM DRP*1 image processing acceleration</p> <p>Max operating frequency: 125MHz-1.5GHz</p> <p>Applications: HMI HD Graphics AI Inferencing Machine Vision Industrial Network Real-time Control</p>

*1 DRP: Dynamically Reconfigurable Processor

RE01- A step change in MCU Power Consumption



Less than 20 μA / MHz active mode brings new opportunities for low power applications in an ever more connected world

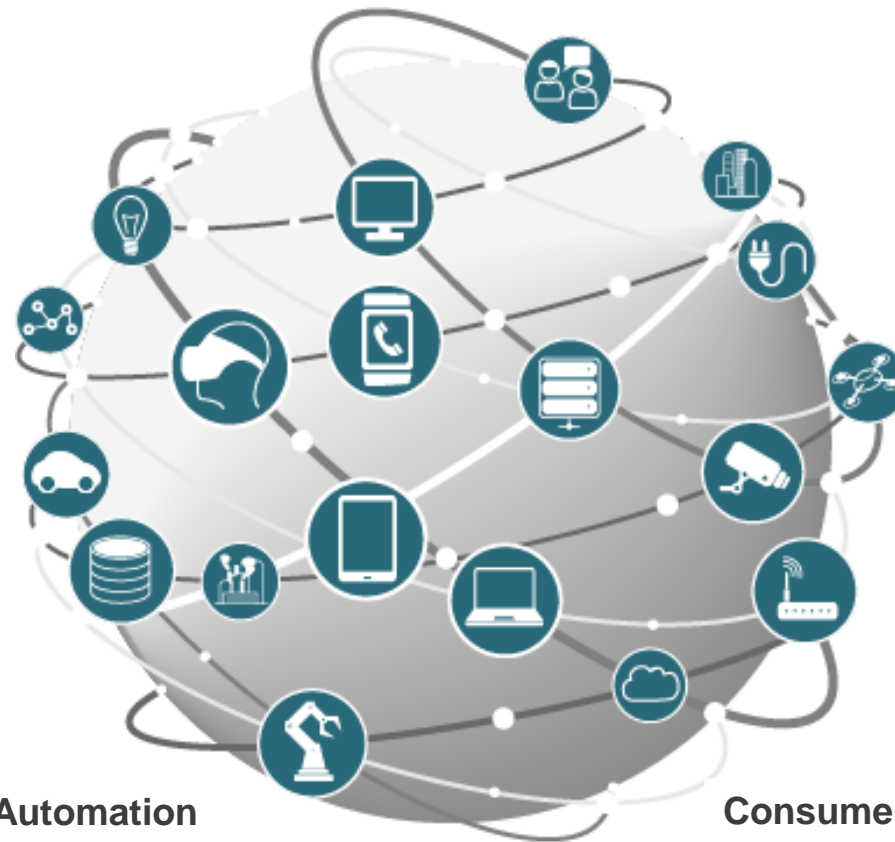


Process Control

Building Automation



Medical



Wearables



Home Automation

Consumer products

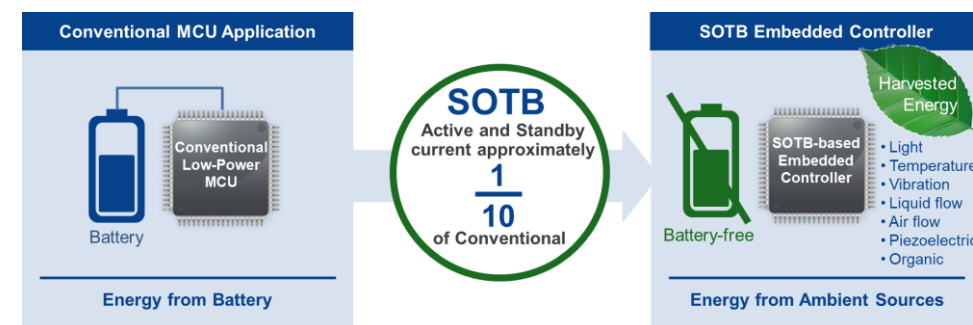
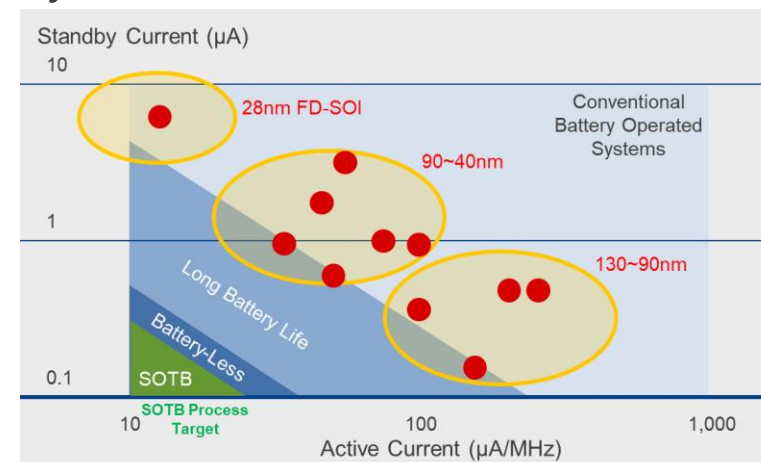


SOTB™ – Silicon On Thin Buried Oxide

DISRUPTIVE EXTREME LOW-POWER TECHNOLOGY

- Enables Microcontroller with market leading low power capability
 - ULP benchmark of 705
- Breaks away from today's silicon restrictions
 - Low active power ≠ Low leakage ≠ high performance
 - Process choice not restricted by desired operating conditions
- Ultra Low Power consumption
 - Active Current: 12 - 35 μA per MHz of operation
 - Standby Current: 100 nA
 - SRAM data retention: Less than 12nA per 32KB of SRAM
 - 4 μA ADC operation @ 32 KHz
 - Unique energy harvesting controller

Silicon on Thin Buried Oxide breaks “the rules” and provides a unique combination low power capabilities



SOTB™ – Silicon On Thin Buried Oxide

DISRUPTIVE EXTREME LOW-POWER TECHNOLOGY

- A Unique process technology targeted at reducing power consumption
- Exclusively from Renesas and protected by many patents
- SOTB breaks previous trade-off between getting either low active current or low standby current

No Compromises		Max. Frequency		Active Current		Standby Current	
		Higher	Lower	High	Low	High	Low
Conventional Technology	Larger Geometry		■	■			■
	Smaller Geometry	■			■	■	
SOTB Technology		■			■		■

SOTB is the Recipe for Very Capable, Extremely Low-Power Applications

Low Active and low Standby Power

High speed operation

High Integration

RE ZERO ENERGY EMBEDDED CONTROLLERS

IMPLEMENTED ON SOTB

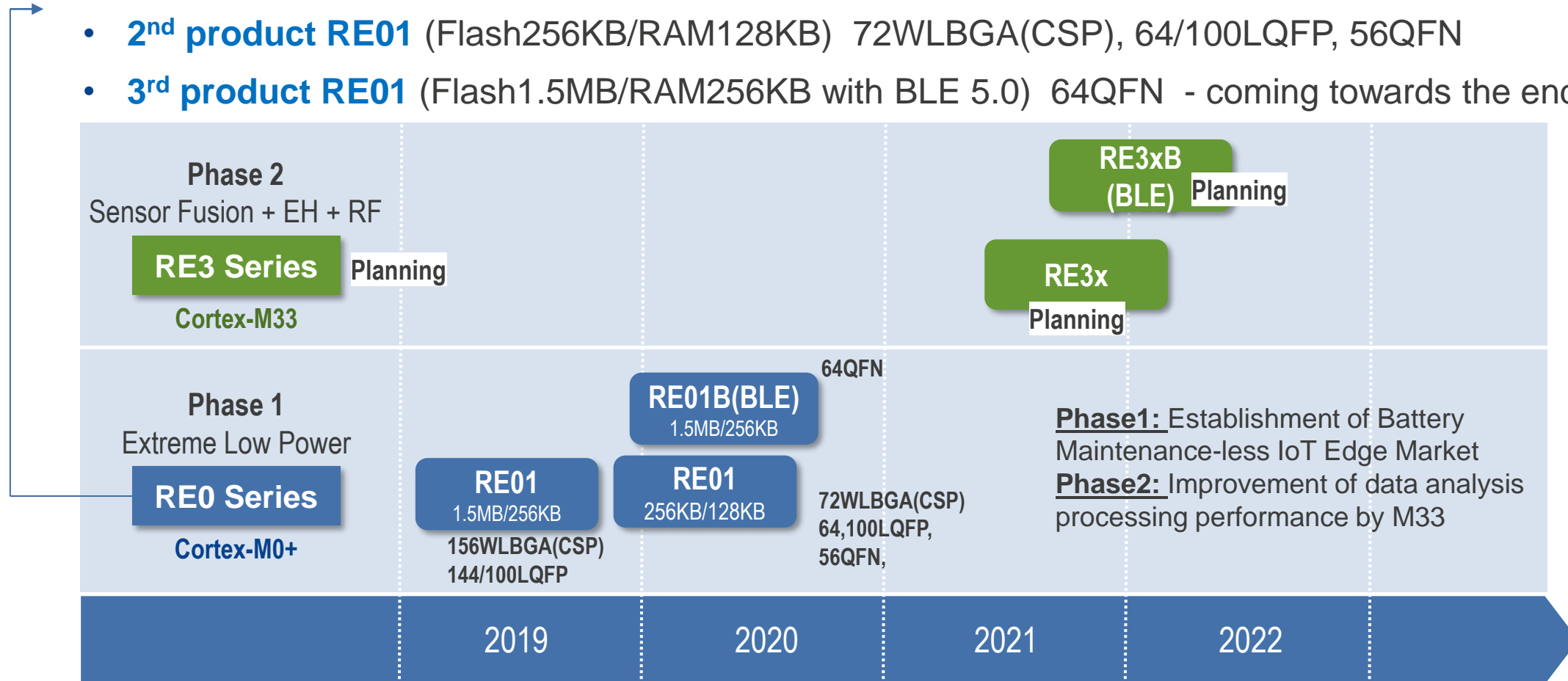
Embedded Controllers implemented on Renesas's unique, ultra low power, Silicon on Thin Buried Oxide (SOTB) process technology

- Low active and low standby current
- Low voltage operation (1.62v) at high speed (64 MHz)
- Unique ultra low power peripherals
- Ultra Low Power analogue and digital peripherals
- Unique support for Energy Harvesting
- RE provides an ideal solution for any low power Applications

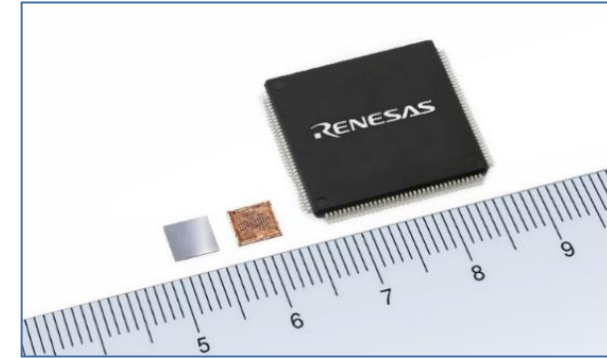
RE FAMILY ROADMAP

IMPLEMENTED ON SOTB

- **1st product RE01** (Flash1.5MB/RAM256KB) 156WLBGA(CSP), 100/144LQFP
- **2nd product RE01** (Flash256KB/RAM128KB) 72WLBGA(CSP), 64/100LQFP, 56QFN
- **3rd product RE01** (Flash1.5MB/RAM256KB with BLE 5.0) 64QFN - coming towards the end of 2020



RE01 1.5 MB SOTB EMBEDDED CONTROLLER



- CPU: Arm Cortex-M0+
- Operating frequency: Up to 32 MHz, and up to 64 MHz in boost mode
- Memory: Up to 1.5 MB flash, 256 KB SRAM
- Current consumption
 - Active: 15* - 35 μ A/MHz
 - Deep Standby: 140 nA with real-time clock source and reset manager
 - Software Standby: 600 nA with retention of core logic and 256 KB SRAM data, real-time clock source, reset manager
 - SRAM data retention: Less than 12nA per 32KB of SRAM
- Energy Harvesting Controller (EHC):
- Trusted Secure IP (TSIP)
- 1 Msps 14-bit ADC, 1.6K Samples/sec @ 32 KHz 4 μ A consumption
- Tiny 156 pin WLPGA package 4.2 x 4.5 mm²

*Bypass of internal LDO mode

RE01 – 1.5 MBYTE EMBEDDED CONTROLLER

ULTRA LOW POWER MCU WITH ENERGY HARVESTING CONTROLLER

Features

- Operating Voltage : 1.62V to 3.6V
- Operating temperature : -40°C to 85°C
- GPIO pins: up to 110 pins
- External clock oscillators
 - 8 to 32 MHz, 32.768 kHz
- PLL : 32, 48, 64 MHz
- On-chip clock oscillators
 - LOCO 32.768 kHz
 - MOCO 2 MHz
 - HOCO 24/32/48/64 MHz
- Ultra-low power by SOTB
 - 35uA/MHz Active (internal LDO mode)
 - 15uA/MHz Active (ext. DCDC mode)
 - 500nA Standby with 32KB RAM retention
 - 120nA Deep standby
- Energy Harvesting Controller (5uA bootup)
- Ultra-low power ADC (at 4uA)
- Ultra-low power HMI (2DG + 8-bit MIP)
- Crypto engine for security with Root of Trust
- Packages : WLBGA156, LQFP144/100

64-MHz ARM® Cortex®-M0+ CPU

RE01

DIV | NVIC | SWD | MTB

Memory

Code Flash (1.5 MB)

SRAM (256 KB)

Analog

14-Bit A/D Converter (18 ch.)

12-Bit D/A Converter x 1

Vref out

Analog Comparator x1

Temperature Sensor

Motor Driver for Watches

Timing & Control

General PWM Timer 32-Bit x 2

General PWM Timer 16-Bit x 4

Asynchronous 16-bit AGT x 2

CCC

8-bit Timer x 2

Low Speed Clock Timer

RTC

HMI

Memory In Pixel Display parallel Interface

2D Graphics Data Conversion Circuit

LED driver

Connectivity

USART w/o FIFO x 5
w/ FIFO x 2

SPI x 2

IIC x 2

QSPI x 1

USB x 1

System & Power Management

DMA Controller x 4

Data Transfer Controller

Event Link Controller

Low Power Modes

Multiple Clocks

CCC

SysTick

Energy Harvesting Controller

Safety

Flash Access Window

ADC Diagnostics

ADC Disconnection Detection

Clock Accuracy Circuit

CRC Calculator

Data Operation Circuit

Port Output Enable for GPT

Independent WDT

Security & Encryption

TSIP - Lite

128-Bit Unique ID

TRNG

AES (128/256)

Hidden Root Key

Flash Access Window

Flash ID Code Protection

MPU x 4

RE01 256K SOTB EMBEDDED CONTROLLER

- CPU: Arm Cortex-M0+
- Operating frequency: Up to 32 MHz, and up to 64 MHz in boost mode
- Frequency Lock Loop (FLL) enables 0.5 % HOCO accuracy -40 → +85 degrees C
- Memory: 256 KB flash, 128 KB SRAM
- Ultra low Current consumption
 - Active: 12* - 25 μ A/MHz
 - Deep Standby 100nA
(350nA with full real-time clock and reset manager)
 - SRAM data retention: Less than 12nA per 32KB of SRAM
- Unique Low power peripherals
 - Wake Up Timer with 30 nA operation
 - RTC with 100 nA operation
 - 1 Msps 14-bit ADC, 1.6K Samples/sec @ 32 KHz 4 μ A consumption
- Energy Harvesting Controller (EHC)
- Trusted Secure IP (TSIP)
- Tiny 72 pin WLPGA package 2.9 x 3.1 mm²

*Bypass of internal LDO mode

RE01-256K MICROCONTROLLER

ULTRA LOW POWER MCU WITH ENERGY HARVESTING CONTROLLER

Features

- Operating Voltage : 1.62V to 3.6V
- Operating temperature : -40°C to 85°C
- GPIO pins: up to 74
- External clock oscillators
 - 8 to 32 MHz, 32.768 kHz
- On-chip clock oscillators
 - LOCO 32.768 kHz
 - MOCO 2 MHz
 - HOCO 24/32/48/64 MHz
- Ultra-low power by SOTB
 - 25uA/MHz Active (internal LDO mode)
 - 12uA/MHz Active (ext. DCDC mode)
 - 400nA Standby with 32KB RAM retention
 - 100nA Deep standby
- Energy Harvesting Controller (5uA bootup)
- Ultra-low power HMI (2DG + 8-bit MIP)
- Ultra-low power ADC (at 4uA)
- Crypto engine for security with Root of Trust
- Packages : WLPGA72, LQFP64/100, QFN56,

64-MHz ARM® Cortex®-M0+ CPU

RE01

DIV | NVIC | SWD | MTB

Memory

Code Flash (256KB)

SRAM (128 KB)

Analog

14-Bit A/D Converter (18 ch.)

Vref out

Temperature Sensor

Timing & Control

General PWM Timer 32-Bit x 2

General PWM Timer 16-Bit x 4

Asynchronous 16-bit AGT x 2

Asynchronous 32-bit AGT x 2

WUPT

LST

CCC

8-bit Timer x 2

RTC

HMI

Memory In Pixel Display parallel Interface

2D Graphics Data Conversion Circuit

Key Interrupt

Connectivity

USART w/o FIFO x 5
w/ FIFO x2

SPI x2

IIC x2

QSPI x 1

System & Power Management

DMA Controller x 4

Data Transfer Controller

Event Link Controller

Low Power Modes

Multiple Clocks

CCC

SysTick

Energy Harvesting Controller

Safety

Flash Access Window

ADC Diagnostics

ADC Disconnection Detection

Clock Accuracy Circuit

CRC Calculator

Data Operation Circuit

Port Output Enable for GPT

Independent WDT

Security & Encryption

TSIP - Lite

128-Bit Unique ID

TRNG

AES (128/256)

Hidden Root Key

Flash Access Window

Flash ID Code Protection

MPU x 4

RE01 GROUP SPECIFICATION









		RE01_256KB (NOTE) Flash/SRAM=256KB/128KB(Under development)				RE01_1.5MB Flash/SRAM=1.5MB/256KB (MP)			
Pin count		100	64	72	56	156	144	100	
Current consumption	while(1) Disabled Peripheral	25uA/MHz@32MHz				35uA/MHz@32MHz			
	Standby current	400nA@1.8V (typ) 500nA@3.3V (typ)				500nA@1.8V (typ) 800nA@3.3V (typ)			
PKG		LQFP		WLBGA	QFN	WLBGA	LQFP	LQFP	
Code Flash / SRAM		256KB / 128KB				1.5MB / 256KB			
CPU Freq		Up to 64MHz (Boost mode), up to 32MHz (Normal mode), up to 32kHz (Low leakage mode)							
Clock		MainOSC, SubOSC, HOCO, MOCO, LOCO (PLL is not available)				PLL, MainOSC, SubOSC, HOCO, MOCO, LOCO			
Timers	GPT32/16					6ch			
	AGT 16bit asynchronous timer					2ch			
	AGTW 32bit asynchronous timer	2ch				NA			
	TMR,RTC,CCC,WDT,IWDT					2ch,1ch,1ch,1ch,1ch			
Serial communication	SCI(UART/IIC/SPI)	5ch (w/o FIFO) + 2ch (w FIFO)							
	RIIC	2ch	1ch	2ch	1ch	2ch			
	SPI	1ch(128bit buffer) + 1ch (32bit buffer)							
	QSPI	1ch							
	USB	NA				1ch			
Analog	S14AD 14bit ADC	12ch	8ch	12ch	7ch	18ch		12ch	
	R12DA 12bit DAC	NA				1ch			
	TEMP Sensor	1ch							
	Analog Comparator	NA				1ch			
	VREF	1ch							
	LED (for watch)	NA				3ch		NA	
HMI	MIP-LCD parallel IF	Supported							
	Motor driver (watch movement)	NA				3ch	NA		
Graphic	GDT 2D Graphic	Supported							
Security	TSIP-Lite AES/TRNG/Key protection)	Supported(Optional) / Not Supported							

RE01 GROUP LINEUP

SCHEDULE IS SUBJECT TO CHANGE



- RE01_1.5MB Mass production Today
- RE01_256KB limited samples available now for some package options MP starts from 3Q '20.

Precuts,		56 QFN	64 LQFP	72 WLBGA	100 LQFP	144 LQFP	156 WLBGA
							
ROM/ RAM	TSIP (Security)	7 x 7mm 0.4mm pitch	10 x 10 mm 0.5mm pitch	3.16x2.88 mm 0.3mm pitch	14 x 14 mm 0.5mm pitch	20 x 20mm 0.5m pitch	4.27 x 4.47mm 0.3mm pitch
1.5MB/ 256KB	Yes	-	-	-	R7F0E015D2CFP MP NOW	R7F0E015D2CFB MP NOW	R7F0E017D2DBN MP NOW
	No	-	-	-	R7F0E014D2CFP MP NOW	R7F0E014D2CFB MP NOW	R7F0E016D2DBN MP NOW
256KB/ 128KB	Yes	R7F0E01182DNG Sample Avl MP '21_Q1	R7F0E01182CFM Sample Avl MP '20_Q3	R7F0E01182DBR Sample '20Q2 MP '21_Q1	R7F0E01182CFP Sample Avl MP '20_Q3	-	-
	No	R7F0E01082DNG MP '21_Q1	R7F0E01082CFM MP '20_Q3	R7F0E01082DBR MP '21_Q1	R7F0E01082CFP MP '20_Q3	-	-

RE01 EMBEDDED CONTROLLER

ULTRA LOW POWER BLE MCU WITH ENERGY HARVESTING CONTROLLER

Preliminary Specification
Samples Q4 2020

Features

- Operating temperature range: -40°C up to 85°C
- GPIO pins: 26
- Main clock oscillator (MOSC)
 - ✓ 8 to 32 MHz when VCC = 1.62 – 3.6 V
- Sub-clock oscillator (SOSC) 32.768 kHz
- High-speed on-chip oscillator (HOCO)
 - ✓ 24, 32, 48, 64 MHz when VCC = 1.62 – 3.6 V
- Middle speed on-chip OSC (MOCO) 2 MHz
- PLL from MOSC – Output Up to 64 MHz
- Low-speed on-chip oscillator (LOCO) 32.768 kHz
- Clock correction circuit (SOSC / LOCO)
- Independent watchdog timer OCO 16 kHz
- Packages QFN64

64-MHz ARM® Cortex®-M0+ CPU

RE01B

DIV | NVIC | SWD | MTB

Memory

Code Flash (1.5 MB)

SRAM (256 KB)

Analog

14-Bit A/D Converter (18 ch.)

Vref out

Temperature Sensor

Timing & Control

General PWM Timer 32-Bit x 1

General PWM Timer 16-Bit x 1

Asynchronous 16-bit AGT x 2

8-bit Timer x 2

Low Speed Clock Timer

RTC

HMI

2D Graphics Data Conversion Circuit

Connectivity

Serial Communications Interface w/ FIFO x 2

SPI

IIC

BLE 5.0

System & Power Management

DMA Controller

Data Transfer Controller

Event Link Controller

Low Power Modes

Multiple Clocks

CCC

SysTick

Energy Harvesting Controller

Safety

Flash Area Protection

ADC Diagnostics

Clock Correction Circuit

Clock Accuracy Circuit

CRC Calculator

Data Operation Circuit

Port Output Enable for GPT

IWDT & WDT

Security & Encryption

TSIP - Lite

128-Bit Unique ID

TRNG

AES (128/256)

MPU x 4

RE01 EMBEDDED CONTROLLER

ULTRA LOW POWER MCU WITH ENERGY HARVESTING CONTROLLER

Preliminary Specification
Available 2021

Features

- Operating temperature range: TBC
- GPIO pins: TBC
- Main clock oscillator (MOSC)
- Sub-clock oscillator (SOSC) 32.768 kHz
- High-speed on-chip oscillator (HOCO)
- Middle speed on-chip OSC (MOCO)
- Low-speed on-chip oscillator (LOCO)
- Clock correction circuit (SOSC / LOCO)
- Independent watchdog timer OCO
- Packages TBC

100-MHz ARM® Cortex®-M33 CPU

RE3x

TZ | NVIC | SWD | MTB

Memory

Code Flash (512 KB)

SRAM (256 KB)

Analog

14-Bit A/D Converter (20 ch.)

Vref out

12-Bit D/A Converter x 1

Low-Power Analog
Comparator x1

Temperature Sensor

Timing & Control

General PWM Timer 32-Bit x 2

General PWM Timer 16-Bit x 4

Asynchronous 16-bit AGT x 2

Asynchronous 32-bit AGT x 2

WUPT LST

8-bit Timer x 2

RTC

HMI

LCD Display
32 X 4 / 28 x 8

LED driver

Cap Touch

Connectivity

Serial Communications
Interface x 7
2 x FIFO

SPI x2

IIC x2

QSPI x 1

USB x 1

System & Power Management

DMA Controller

Data Transfer Controller

Event Link Controller

Low Power Modes

Multiple Clocks

CCC

SysTick

Energy Harvesting Controller

Safety

Flash Area Protection

ADC Diagnostics

Clock Correction Circuit

Clock Accuracy Circuit

CRC Calculator

Data Operation Circuit

Port Output Enable for GPT

IWDT & WDT

Security & Encryption

TSIP

128-Bit Unique ID

TRNG

AES / ECC

MPU x 4

RE01 EMBEDDED CONTROLLER

ULTRA LOW POWER BLE MCU WITH ENERGY HARVESTING CONTROLLER

Preliminary Specification
Available 2021

Features

- Operating temperature range: TBC
- GPIO pins: TBC
- Main clock oscillator (MOSC)
- Sub-clock oscillator (SOSC) 32.768 kHz
- High-speed on-chip oscillator (HOCO)
- Middle speed on-chip OSC (MOCO)
- Low-speed on-chip oscillator (LOCO)
- Clock correction circuit (SOSC / LOCO)
- Independent watchdog timer OCO
- Packages TBC

100-MHz ARM® Cortex®-M33 CPU

RE3xB

TZ | NVIC | SWD | MTB

Memory

Code Flash (2.0 MB)

SRAM (512 KB)

Analog

14-Bit A/D Converter (20 ch.)

Vref out

12-Bit D/A Converter x 1

Low-Power Analog
Comparator x1

Temperature Sensor

Timing & Control

General PWM Timer 32-Bit x 2

General PWM Timer 16-Bit x 4

Asynchronous 16-bit AGT x 2

Asynchronous 32-bit AGT x 2

WUPT LST

8-bit Timer x 2

RTC

HMI

LCD Display
32 X 4 / 28 x 8

LED driver

Cap Touch

Connectivity

Serial Communications
Interface x 7
2 x FIFO

SPI x2

IIC x2

QSPI x 1

USB x 1

BLE 5.0 x 1

System & Power Management

DMA Controller

Data Transfer Controller

Event Link Controller

Low Power Modes

Multiple Clocks

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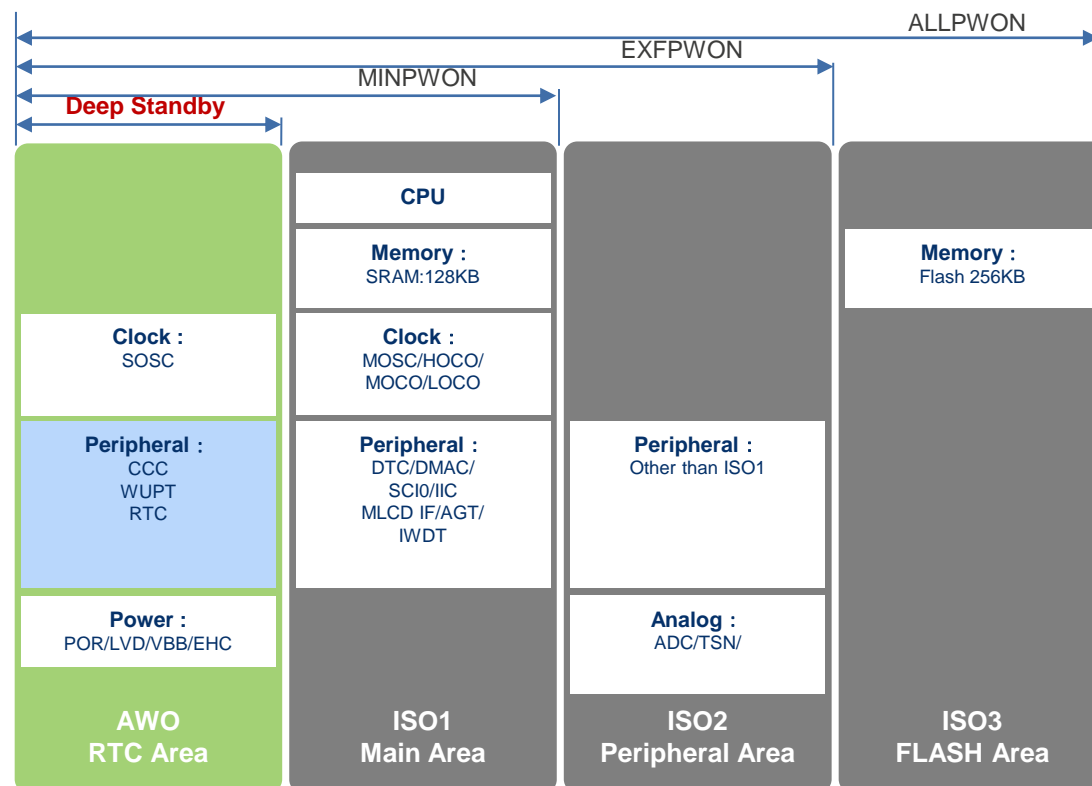
TRNG

AES / ECC

MPU x 4

RE01 LOW POWER SYSTEM (256K VERSION)

- Power supply modes enable to turn off the power of each power domain



Power Supply Mode↓	AWO	ISO1	ISO2	ISO3
ALLPWON	On	On	On	On
EXFPWON	On	On	On	Off
MINPWON	On	On	Off	Off
Deep-standby	On	Off	Off	Off

RE01 LOW POWER SYSTEM (256K VERSION)

OPERATING MODES

Measurement Conditions

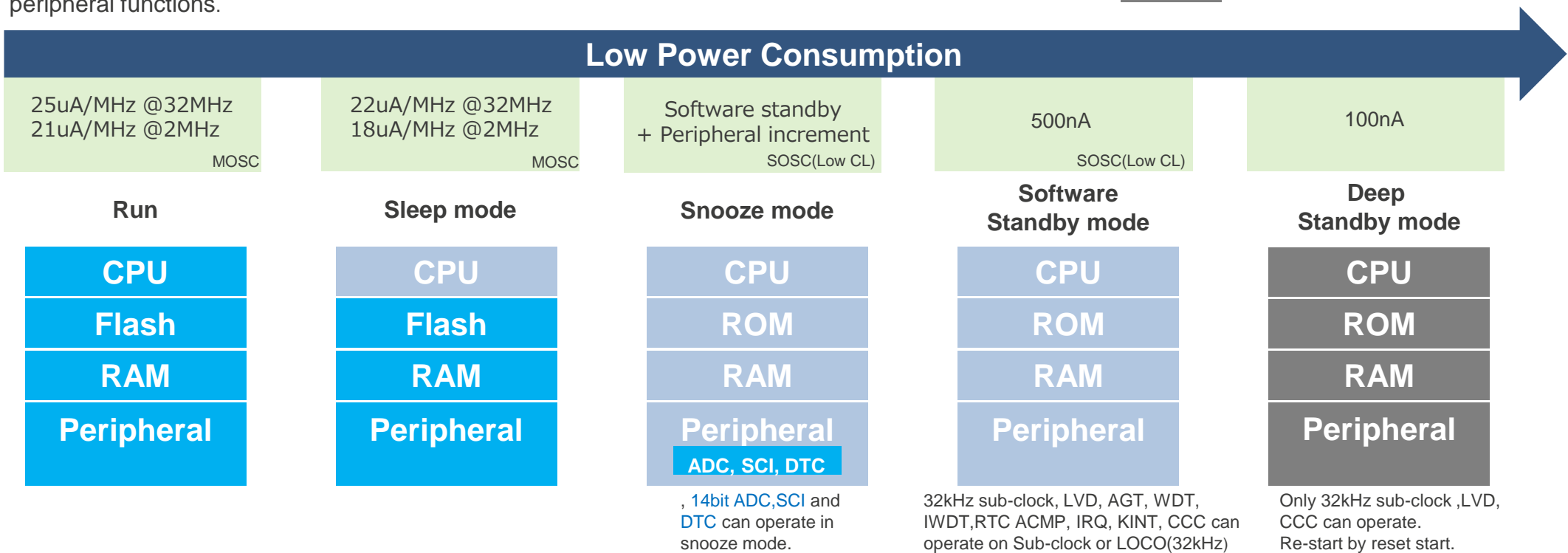
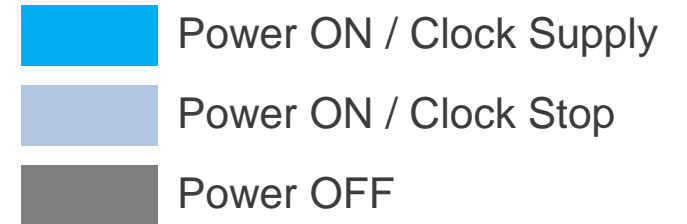
VCC: 3.3V

Program: while(1) operation (peripheral clock signal stopped)

Program execution from flash @ 32 MHz, execution from SRAM @ 2 MHz)

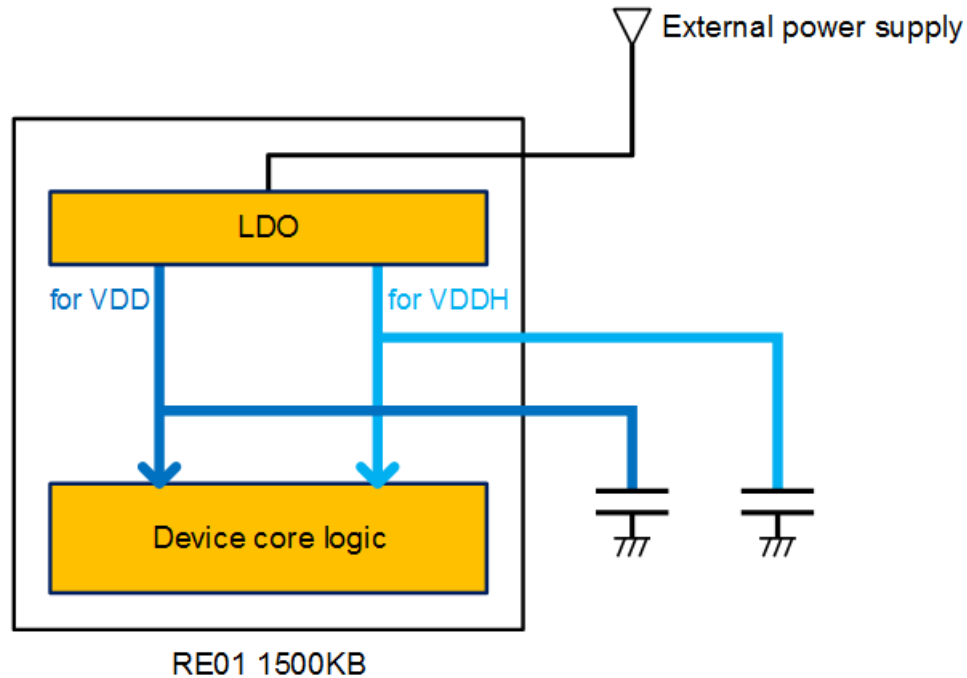
Test conditions: Peripheral clock divided by 64

Current consumption in normal operation depends on the code executed and the number of operating peripheral functions.



RE01 POWER SUPPLY OPTIONS

ISL9123 recommended



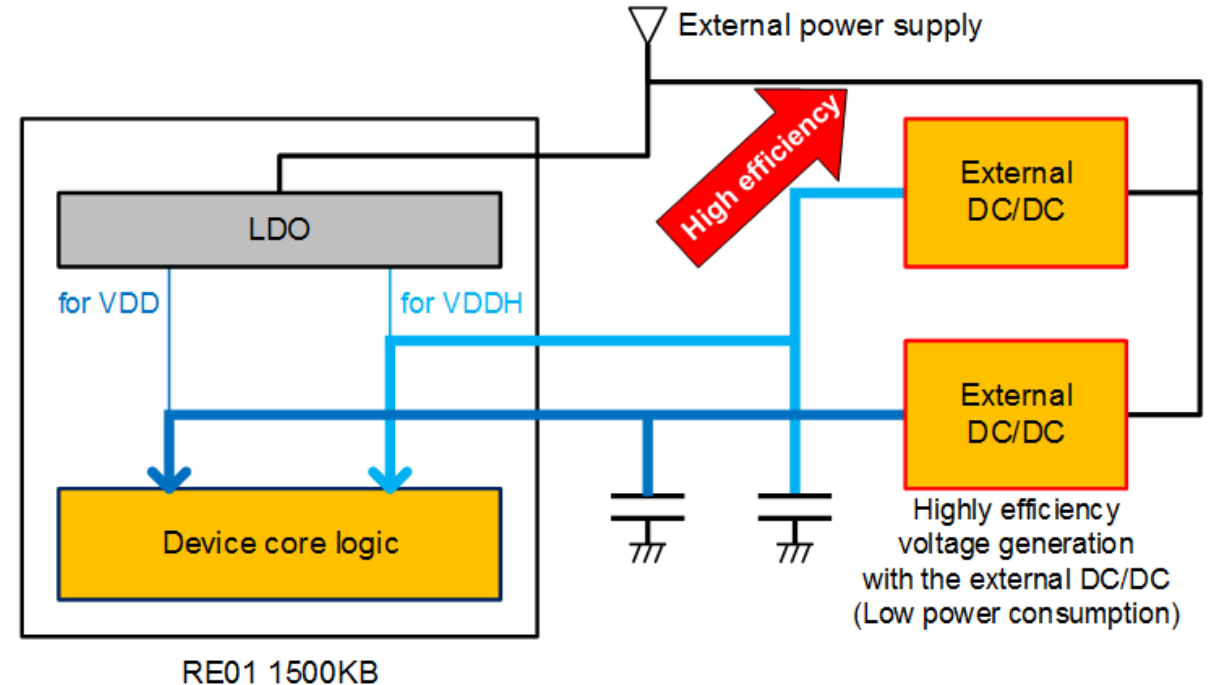
Using the internal LDO (Normal case)

Internal LDO Mode

RE01-256K 25 μ A/MHz

RE01- 1.5M 35 μ A/MHz

Controlled by LDO Cut register LDOCUT



Low power consumption by the external DC/DC

Internal LDO OFF, external DC-DC

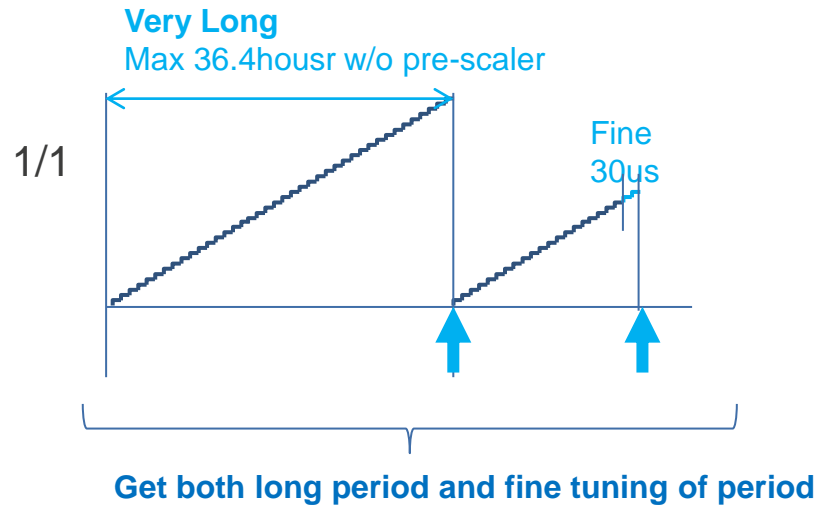
RE01-256K 12 μ A/MHz

RE01- 1.5M 15 μ A/MHz

RE01 ASYNCHRONOUS 32 BIT TIMER (AGT-32)

AGTW x 2ch 32bit counter

32bit=4,294,967,296count



Ideal solution to applications that need to stay asleep for long periods of time with minimum power consumption such as IoT sensors

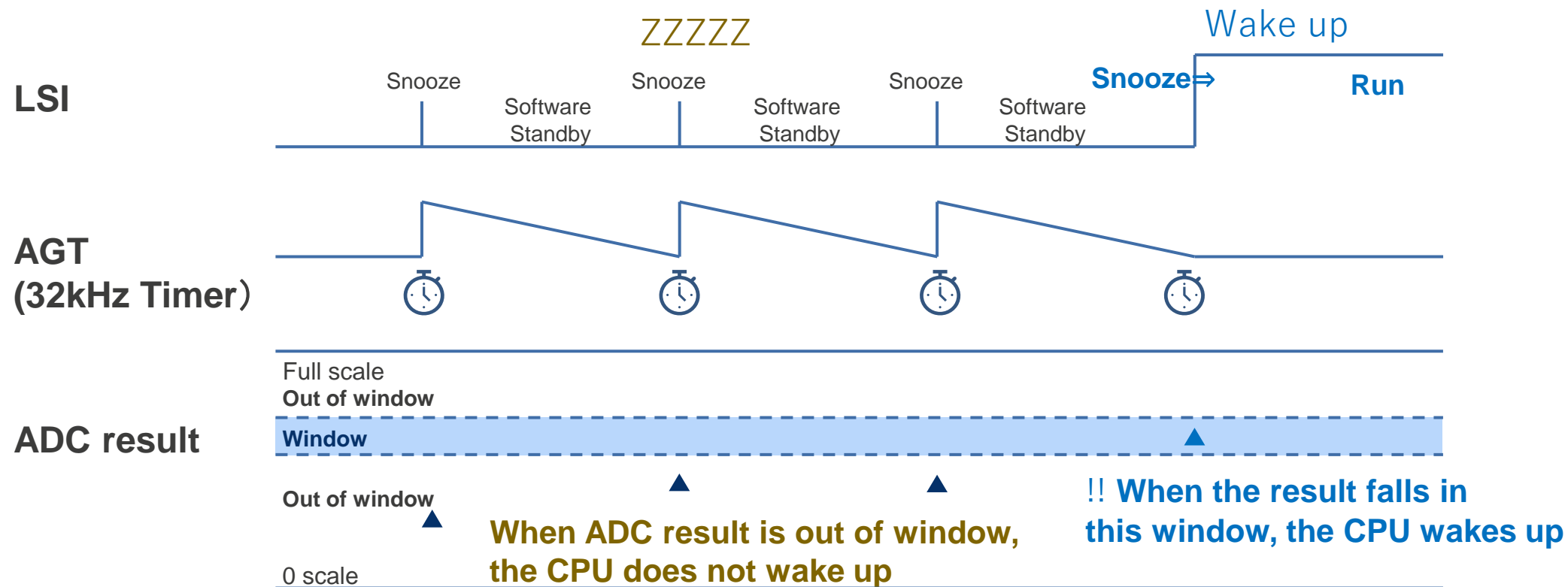
- AGT -32 offers huge range of timeouts
 - Max Timeout 36.4 hrs, 30 uS resolution
 - Max timeout 194 days, 3.9 mS resolution
 - 400 nA Icc SSTBY + 38 nA AGT-32 = 438 nA@ 1.8v

**Also available Ultra low power wake Up Timer
WUPT, available in deep standby
100 nA (DSTBY)+ 100 nA (SOSC) + 30 nA = 230 nA@1.8v
Max timeout 36.4 hrs accurate to 30 uS resolution**

RE01-256K only

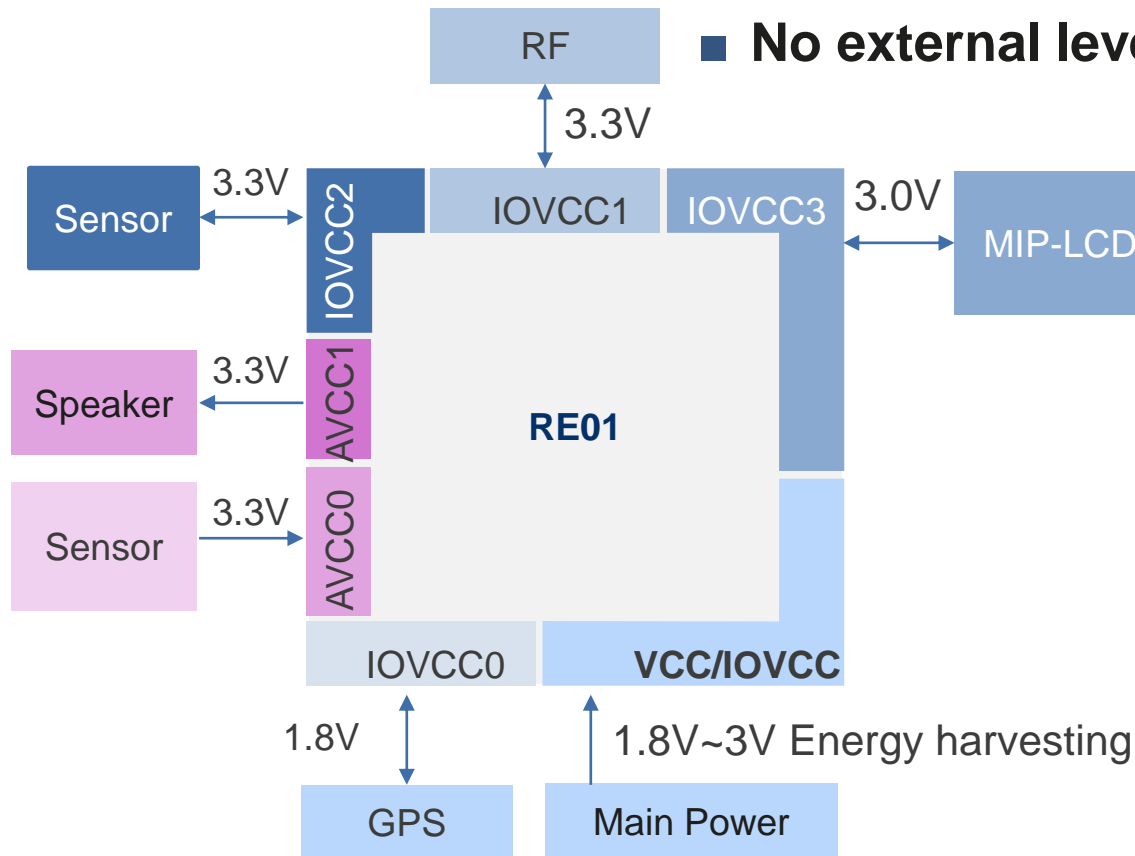
RE01 LOW POWER SYSTEM - SNOOZE MODE

- In intermitted operation, snooze mode enables to avoid unnecessary wake up which causes waste of power.



RE01 SUPPLY VOLTAGE FLEXIBILITY

- Supports **independent digital and analog IO power domains** to support connection to external devices with different operating voltages
- **No external level shifters** are needed

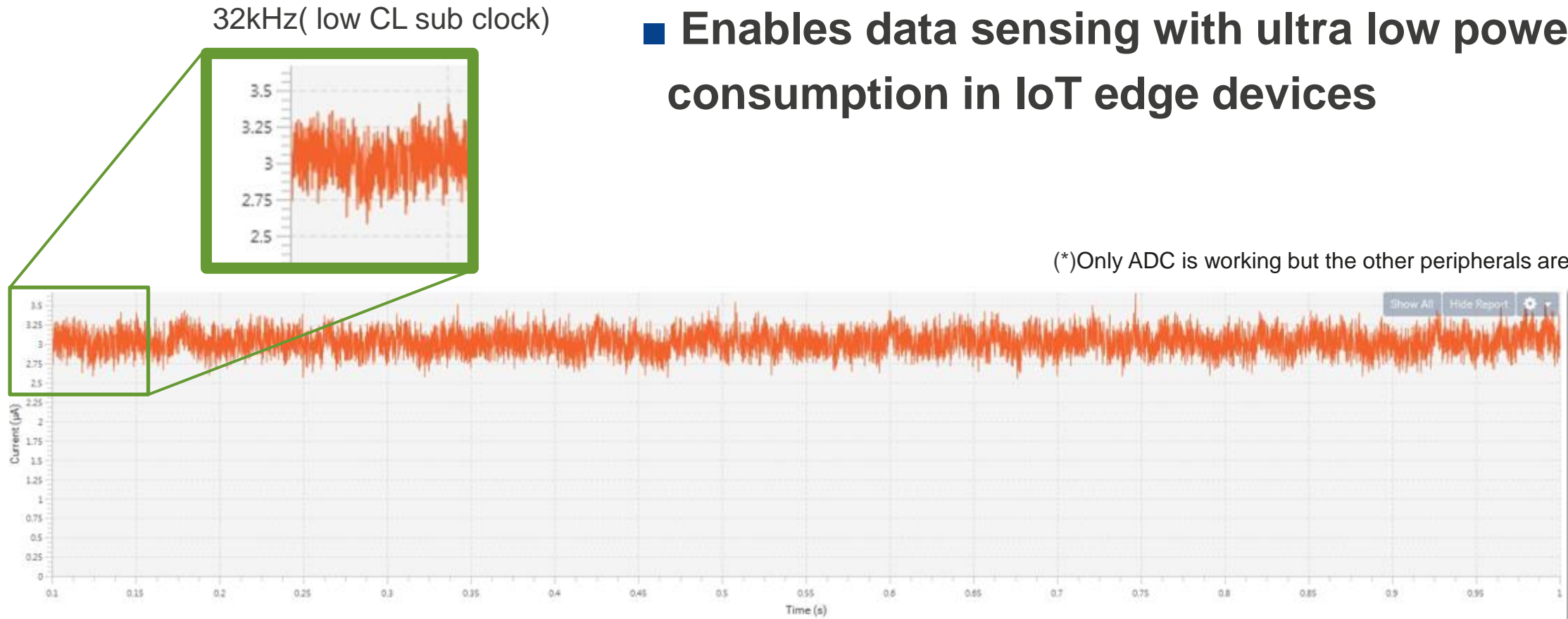


Item	Value	Unit
Power Supply voltage for System (VCC/IOVCC)	1.62 to 3.6V	System
Power Supply voltage for IO0 (IOVCC0)	1.62 to 3.6V	General I/O and SPI etc...
Power Supply voltage for IO1 (IOVCC1)	1.62 to 3.6V	General I/O and MIP etc...
Power Supply voltage for IO2 (IOVCC2)	1.62 to 3.6V	General I/O
Power Supply voltage for Analog-IP (AVCC0)	1.62 to 3.6V	14bADC, TSN, VREF
Power Supply voltage for Analog-IP (AVCC1)	1.62 to 3.6V	DAC, ACMP
Power Supply voltage for USB (USBVCC)	3.0 to 3.6V	USB transceiver

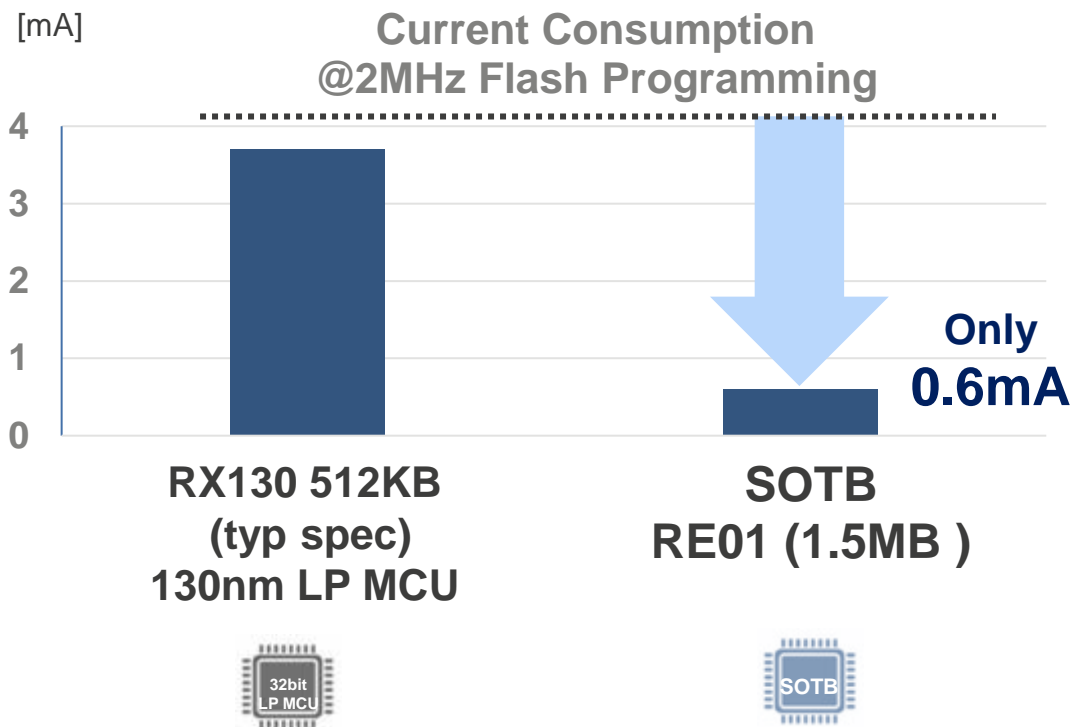
RE01 – 1.5 Mbyte

RE01 ULTRA LOW POWER, ALWAYS-ON SENSING

- 4 μ A (32kHz low CL) *
- Enables data sensing with ultra low power consumption in IoT edge devices

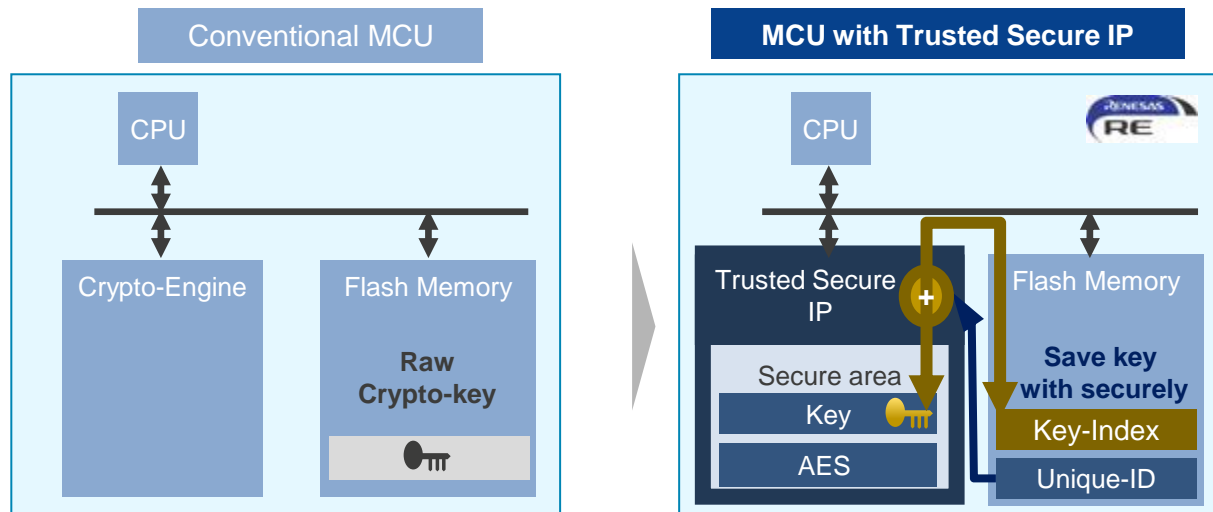


RE01 ULTRA LOW POWER FLASH PROGRAMMING



- Flash programming with only 0.6mA
- Reducing battery depletion concerns for Over-The-Air IoT FW updates

RE01 SECURITY - TSIP (TRUSTED SECURE IP)



- Trusted Secure IP creates secure area inside the RE by monitoring and controlling unauthorized access. It secures the operation of the encryption engine and of any encryption keys.
- When storing the encryption key outside the TSIP, it is encrypted and scrambled with the unique ID to make it unusable outside one

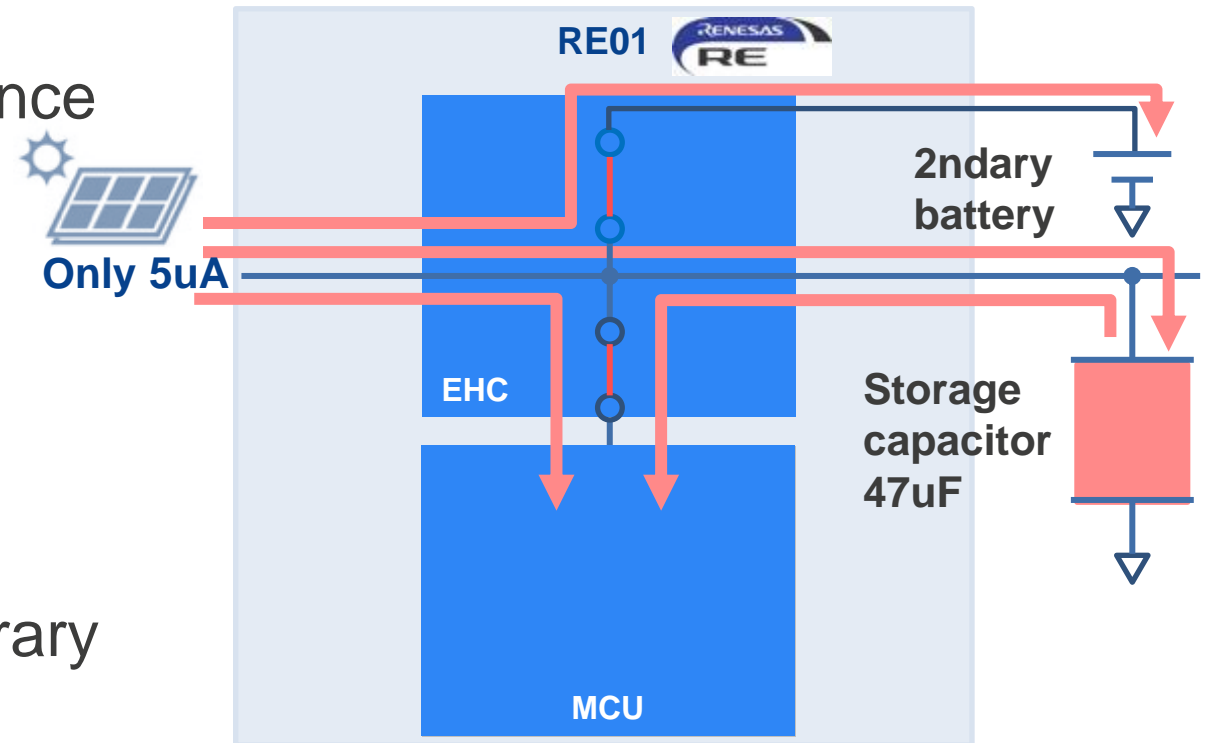
Security features on RE01

IP	function	details	
TSIP	AES	Key length	128bit/256bit
		Hidden Root Key	Supported
		Modes	ECB, CBC, CTR, CMAC, CCM, GCM, XTS
	TRNG	128bit/256bit	
	Unique-ID	Used to generate key index	
	Access management	Prevent unauthorized access	
Flash	Flash area protection	Used for secure-boot and secure-OTA to protect authentication program.	
	Flash ID code protection	ID code protection for the flash programming from a host device	

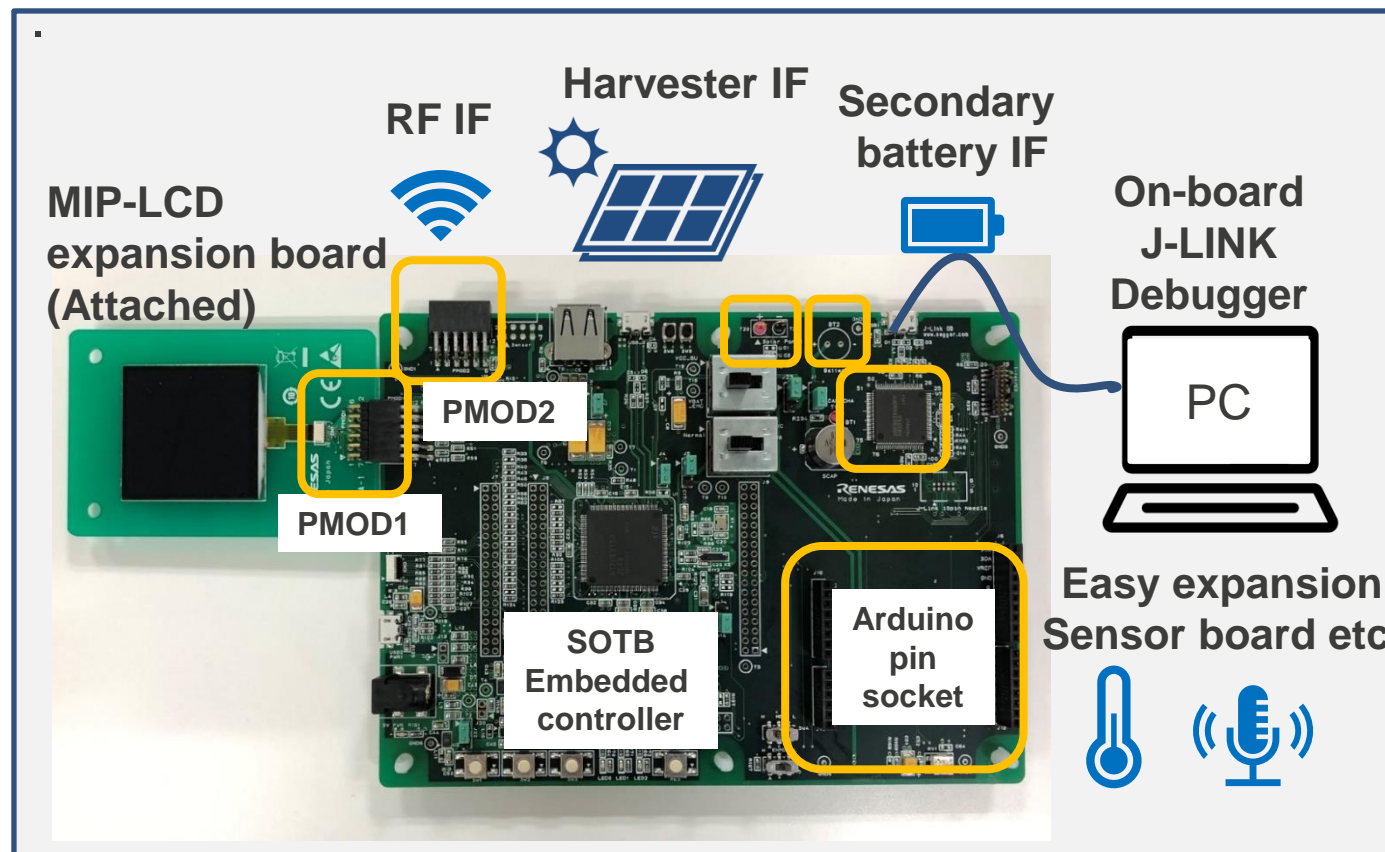


ENERGY HARVESTING CONTROLLER (EHC)

- Multiple power source & charge storage element management
- Autonomous & reliable startup sequence managing inrush current issues
- Overcharge prevention
- Charge detection
- Reverse current protection
- Quick start function
- Simultaneous charge mode for battery/secondary storage and temporary storage/capacitor
- Small start up current 5uA by active management of MCU blocks



EVALUATION BOARD FOR RE01 GROUP



EVB specification

Items	Specification
MCU	R7F0E015D2CFB
Crystal oscillator	SOTB main : 32MHz SOTB sub : 32.768kHz
Debug I/F	USB for J-Link OB
Harvester I/F	Harvester I/F x1, Battery I/F x1
Arduino compatible I/F	2.54mm pitch: 10pin x 1, 8pin x 2 ,6pin x 1
USB serial I/F	Driver : USB I/F IC (Part No: FT230XQ)
PMOD connector	PMOD1 : SPI communication/ MIP-LCD expansion board PMOD2 : QSPI communication
On board memory	SPI serial flash : 64Mbit

Order Code : RTK70E015DS00000BE

INTEGRATED DEVELOPMENT ENVIRONMENT

- IAR is recommended. GCC will also be supported.

		IAR EWARM IAR C/C++ 	Renesas e2 studio GCC ARM 
IAR I-Jet		✓	NA
SEGGER J-Link		✓	✓
Renesas E2		NA	✓

SUMMARY

- Renesas want to enable a new generation of low power applications using the unique low power SOTB process
- The RE enables a new generation of ultra low power applications reducing the size of batteries or increasing product lifetime
- The unique capabilities of the RE with both low active and standby currents as well as high performance at low voltages enable new types of low power applications
- Energy Harvesting applications become possible
- The 1.5 Mbyte RE01 is available now in mass production and samples of the 256K version are also available

Learn more at www.renesas.com/SOTB